



Ra-01SCH Specification

Version

V1.1.0

Copyright

©2022

Disclaimer and copyright notice

The information in this article, including the URL address for reference, is subject to change without prior notice.

The documentation is provided "as is" without any warranty, including any warranties of merchantability, fitness for a particular purpose, or non-infringement, and any warranties mentioned in the proposal, specification or sample. This document is not responsible for any infringement of any patent rights arising out of the use of the information in this document. No license, express or implied, by estoppel or otherwise, is hereby granted.

The test data obtained in this paper are all obtained by Ai-Thinker laboratory , and the actual results may be slightly different.

The Wi-Fi alliance membership mark is owned by the WiFi alliance.

All trade mark names, trademarks and registered trademarks mentioned herein are the property of their respective owners and are hereby declared.

The final interpretation right is owned by Shenzhen Ai-Thinker Technology Co., Ltd.

Note

The contents of this manual may be changed due to the version upgrade of the product or other reasons. Shenzhen Ai-Thinker Technology Co., Ltd. reserves the right to modify the contents of this manual without any notice. This manual is only used as a guide, and Shenzhen Ai-Thinker Technology Co., Ltd. makes every effort to provide accurate information in this manual, but Shenzhen Ai-Thinker Technology Co., Ltd. does not ensure that the contents of the manual are completely true,, All statements and information in this manual. and the recommendations do not constitute for any warranty, express or implied.

Document development/revision/revocation resume

[illegible]

CONTENT

1 Product Overview	5
1.1. Characteristics.....	5
1.2 Main parameters	6
2 Electrical parameters	6
2.1. Electrical character.....	7
2.2. Digital port characteristics	7
2.3. SPI Interface features	7
3 Appearance size	9
4 Pin function	10
5 Schematics.....	11
6 Design guidance	12
6.1 Application Circuit.....	12
6.2 Recommended module package design size	12
6.3 Antenna installation	12
6.4 Power Supply.....	13
6.5 GPIO.....	13
6.6 Software writing	15
7 FAQ.....	16
7.1 Factors affecting transmission distance	16
7.2 Module use reminder	16
7.3 Interfering factors	16
8 Reflow Welding Curve	17
9 Related models and antenna guide	17
9.1 Related models.....	17
9.2 Antenna recommendation.....	18
10 Packaging information.....	19
11 Contact us.....	19

1. Product Overview

LoRa series module Ra-01SCH is designed and developed by Shenzhen Ai-Thinker Technology Co., Ltd. This module is used for ultra-long distance spread spectrum communication. Its RF chip LLCC68 mainly uses LoRa™ remote modem for ultra-long distance spread spectrum communication, with strong anti-interference and low power consumption. LLCC68 chip has a high sensitivity of over-129 dBm, a 20 dBm power output, a long transmission distance and a high reliability with SEMTECH's LoRa™ patent modulation technique. Meanwhile, comparing with the traditional modulation technology, LoRa™ provides significant advantages in both blocking and selectivity over conventional modulation techniques. It solves the problem of simultaneously balance the distance, the anti-interference and the power consumption which the traditional design scheme can't achieve.

Application areas

automatic meter reading, supply chain and logistics, home building automation, security system, remote irrigation system.

1. 1. Characteristics

- LoRa™ modem
- Support FSK、GFSK、MSK、GMSK、LoRa™ and OOK mode
- Frequency supports 803MHz~930MHz
- Operating voltage is 3.3V, Max output transmitting power:+22dBm,Max current:140m
- Low power consumption in a received state, the min received current is 4.2mA, stand-by current is 0.6mA
- High sensitivity: As low as -129dBm
- Support spreading factor:SF5/SF6/SF7/SF8/SF9/SF10/SF11
- Small volume double row stamp hole patch for SMD package
- Adopts SPI interface, half-duplex communication, with CRC, up to 256-byte packet engine
- Compatible with various antenna interface: stamp hole/round hole and IPEX, supports more scheme selection.

1.2 Main parameters

Table 1 main parameters instruction

Model	Ra-01SCH
Package	SMD16
Size	17*16*3.2(±0.2)mm
Antenna	Compatible with half-hole pad/through-hole pad (antennas need to be soldered)/IPEX
Frequency range	803MHz~930MHz
Operating Temperature	-40 ° ~ 85 °
Storage environment	-40 ° ~ 125 ° , < 90%RH
Power supply	2.7~3.6V, typical value 3.3V, recommended current > 200mA
Support Interface	SPI
Programmable bit rate	Max up to 300Kbps
Crystal frequency	32MHz
Transmission distance	In an open environment, this module match with spring antenna the transmitting range can reach 2.8km or match with suction cup antenna the transmitting range can reach 4.6km.

2. Electrical parameters

Ra-01SCH series modules are electrostatic sensitive devices, special precautions need to be taken when handling.

Note:



Ra-01SCH module is electrostatic sensitive devices (ESD) , It requires special ESD precautions and should generally be classified as an ESD sensitive component. During the entire handling, transportation and operation of the Ra-01SCH module, proper ESD handling and packaging procedures should be used. Please do not touch the module with hands or use a non-antistatic soldering iron for soldering, so as not to damage the module.

2.1. Electrical character

Parameter	Name	Min	Typ	Max	Unit	Remarks
Operating temperature	TOPR	-40	25	85	□	Industrial design
Supply voltage	VDD	2.7	3.3	3.6	V	≥3.3V(Guaranteed output power)

2.2. Digital port characteristics

Description		Typ		Unit	
Operating frequency		803~930		MHz	
IO	Name	Min	Typ	Max	Unit
IO level	VIO	2.7	3.3	3.6	V
Low input logic level	VIL	-	-	0.2	V
High input logic level	VIH	0.8	-	-	V
Low output logic level	VOL	-	-	0.1	V
High output logic level	VOH	0.9	-	-	V

2.3. SPI Interface features

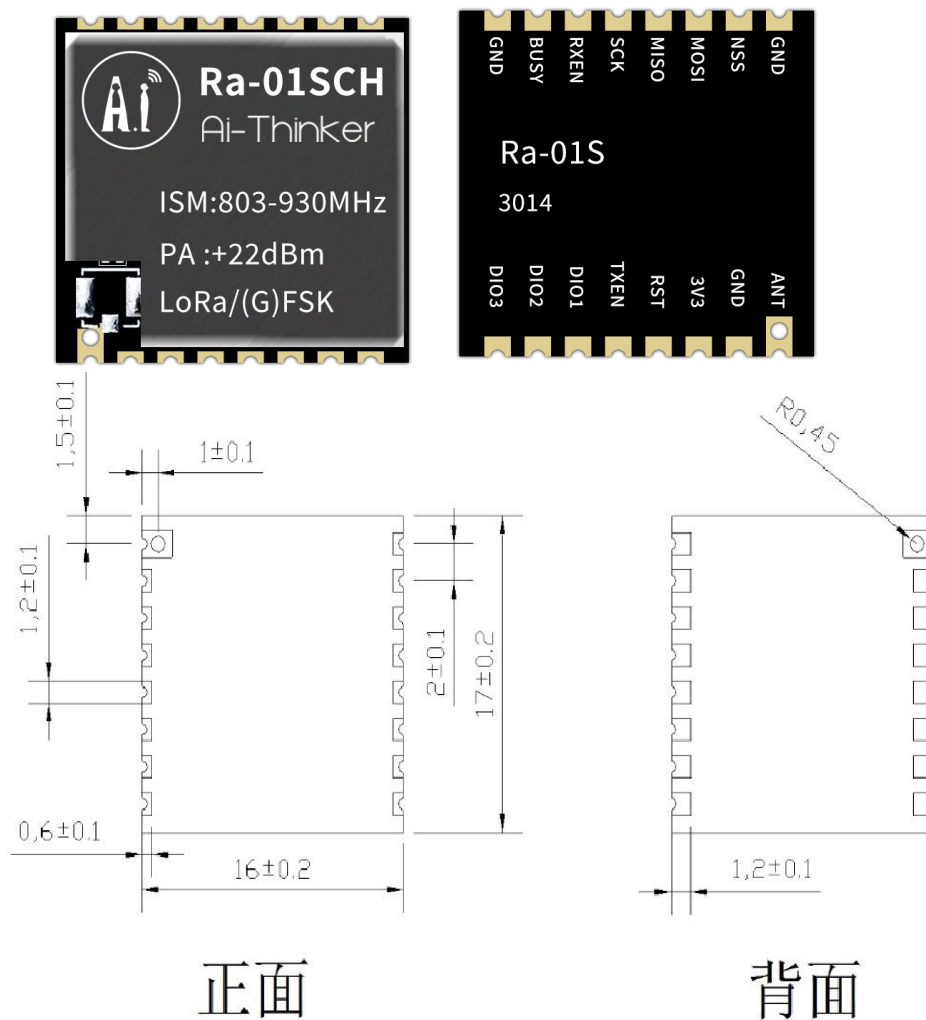
Name	Description	Condition	Min	Typ	Max	Unit
Fsck	SCK frequency	—	—	—	10	MHz
TCH	SCK High level time	—	50	—	—	ns
TCL	SCK Low level time	—	50	—	—	ns
Trise	SCK Rise time	-	-	5	-	ns
Tfall	SCK Fall time	-	-	5	-	ns
Tsetup	MOSI Time setting	From MOSI change to SCK rising edge	30	-	-	ns
Thold	MOSI Duration	Change from rising edge of SCK to MOSI	20	-	-	ns

Tnsetup	NSS Set up time	From NSS falling edge to SCK rising edge	30	-	-	ns
Tnhold	NSS Time maintain	From SCK falling edge to NSS rising edge, normal mode	100	-	-	ns
Tnhigh	SPI Access interval NSS High level time	-	20	-	-	ns
T_DATA	DATA maintenance and set up time	-	250	-	-	ns

3. Appearance size

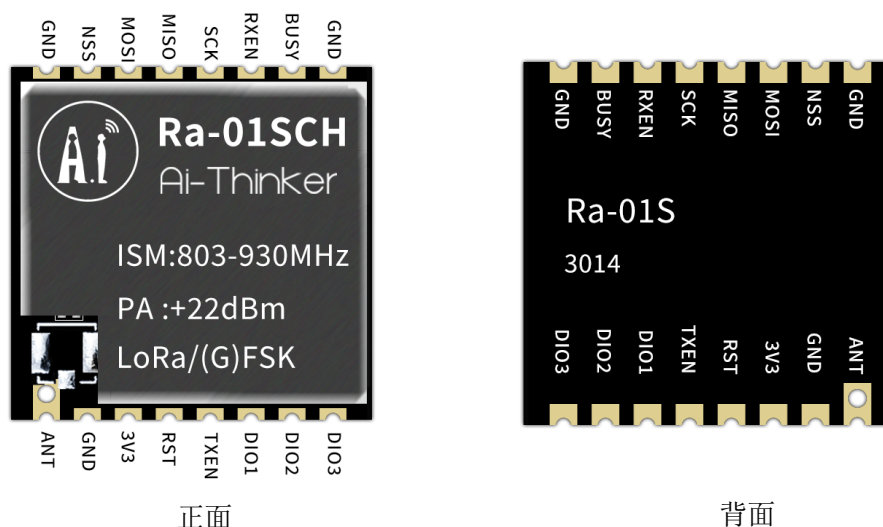
Ra-01SCH has two antenna interface: Default equip with the IPEX, the antenna needs to be led to the motherboard by a half-hole pad. A type with IPEX, the antenna can be directly assembled to the module.
(The rendering is for reference only, the actual product shall prevail)

(1) Default without IPEX version



4. Pin function

Ra-01SCH module is connected to 16 interfaces, refer to pin diagram, pin function definition table is interface definition.



Ra-01SCH Pin diagram

Table Pin function definition

No.	Name	Function instruction
1	ANT	Ground
2	GND	Ground, Connect to the power reference ground
3	3.3V	Typical value 3.3V, recommended current > 200mA
4	RESET	Reset
5	TXEN	RF control port
6	DIO1	Digital IO1 software configuration
7	DIO2	Digital IO2 software configuration
8	DIO3	Digital IO3 software configuration
9	GND	Ground
10	BUSY	Status indicator pin (Be sure to connect to the IO port of the master MCU)
11	RXEN	RF control port
12	SCK	SPI clock input
13	MISO	SPI data output
14	MOSI	SPI data input
15	NSS	SPI chip select input
16	GND	Ground, Connect to the power reference ground

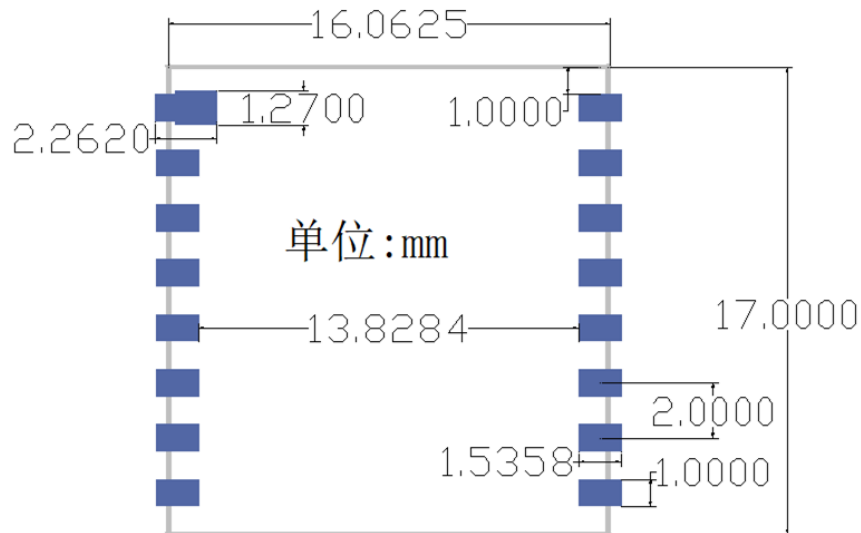
The three general IO pin of LLCC68 can be available in LoRa™ mode.

Their mapping depends on the configuration of the two registers RegDioMapping1 and RegDioMapping2.

Operating Mode	DIOx Mapping	DIO3	DIO2	DIO1
All	00	CadDone	Fhss Change Channel	RxRimeout
	01	Valid Header	Fhss Change Channel	Fhss Change Channel
	10	PayloadCrc Error	Fhss Change Channel	CadDetected
	11	-	-	-

5. Design guidance

5.1 Application Circuit



(1) In addition to the SPI interface, the communication interface with the master MCU must also connect BUSY/DIO1 to the IO port of the master MCU

(2) If the antenna is soldered on the main control board, it is recommended to reserve a Π matching circuit at the antenna interface.

5.2 Recommended module package design size

Note: This is the package drawing of the Ra-01SCH module. It is recommended to design the PCB board according to this drawing so that the module can work normally on the PCB board; and when designing the pads, pay attention to the design of the pads on the PCB. The pad is retracted and offset, and the PCB pad is expanded relative to the module pad without affecting the use of the module.

5.3 Antenna installation

(1) Ra-01SCH needs to be used for soldering antennas, the module is compatible with half-hole pads and round-hole pads;

(2) In order to meet the best antenna effect, the location of the antenna assembly should be far away from the metal parts;

(3) The antenna installation structure has a great influence on the performance of the

module. Make sure that the antenna is exposed, preferably vertically upward. When the module is installed inside the case, you can use a high-quality antenna extension cable to extend the antenna to the outside of the case

(4) The antenna must not be installed inside the metal shell, which will greatly reduce the transmission distance.

5.4 Power Supply

(1) Recommended voltage 3.3 V, Peak: Current over 200mA .

(2) It is recommended to use the LDO power supply; If DC-DC is used, the ripple is controlled within 30 mV.;

(3) DC-DC power supply circuit is recommended to reserve the position of the dynamic response capacitor, and the output ripple can be optimized when the load change is large.;

(4) 3.3V power jack advise to add ESD components.;

(5) When designing the power supply circuit for the module, it is recommended to reserve more than 30% of the power supply current, which is conducive to the long-term stable operation of the whole machine;

(6) Please pay attention to the correct connection of the positive and negative poles of the power supply. Reverse connection may cause permanent damage to the module.

5.5 GPIO

(1) There are some GPIO ports on the periphery of the module. If you need to use a 10-100 ohm resistor in series with the IO port, it can suppress overshoot and make the levels on both sides more stable, which is helpful for EMI and ESD.

(2) For the pull-up and pull-down of special IO ports, please refer to the instructions in the specification, which will affect the startup configuration of the module;

(3) The IO port of the module is 3.3V. If the main control and the IO level of the module do not match, a level conversion circuit needs to be added

(4) If the IO port is directly connected to a peripheral interface, or a terminal such as a header, it is recommended to reserve an ESD device near the terminal of the IO trace.

5.6 Software writing

- (1) This module is LLCC68+ peripheral circuit, users can operate according to LLCC68 chip manual; □
- (2) DIO1,DIO2,DIO3 are general-purpose IO ports, which can be configured into multiple functions;
- (3) The control of the RF switch TX/RX is completed by the internal circuit of the module by default. But the interface is reserved in the design, which can realize external MCU control. If you need external MCU control, please contact Ai-Thinker technicians to replace the module BOM.

Different between LLCC68 and SX1262/SX1268:

- (1) SX1262/SX1268 support spreading factor SF5,SF6,SF7,SF8,SF9,SF10,SF11,SF12; SX1262/SX1268 can set spreading factor and receiving bandwidth:

LoRa@ Rx/Tx, BW = 7.8 - 500 kHz,
SF5 TO SF12,BR=0.018-62.5 Kb/S

- (2) LLCC68 support spreading factor SF5,SF6,SF7,SF8,SF9,SF10,SF11.

LLCC68 can set spreading factor and receiving bandwidth:

LoRa@ Rx/Tx, BW = 125 - 250 - 500 kHz,
LoRa@, SF=5-6-7-8-9 for BW=125kHz,
LoRa@, SF=5-6-7-8-9-10 for BW=250 kHz,
LoRa@, SF=5-6-7-8-9-10-11 for BW=500 kHz;

6. FAQ

6.1 Factors affecting transmission distance

- (1) When there is a straight line communication obstacle, the communication distance will be attenuated accordingly
- (2) Temperature, humidity, and co-frequency interference will increase the communication packet loss rate;
- (3) The ground absorbs and reflects radio waves, the test effect is poor when it is close to the ground
- (4) Sea water has a strong ability to absorb radio waves, so the seaside test results are poor;
- (5) If there is a metal object near the antenna or placed in a metal shell, the signal attenuation will be serious;
- (6) Incorrectly set the power register, and the air speed is set too high (the higher the air speed, the closer the distance)
- (7) The low voltage of the power supply at room temperature is lower than the recommended value, the lower the voltage, the lower the power output;;
- (8) The poor matching degree of the antenna and the module or the quality of the antenna itself

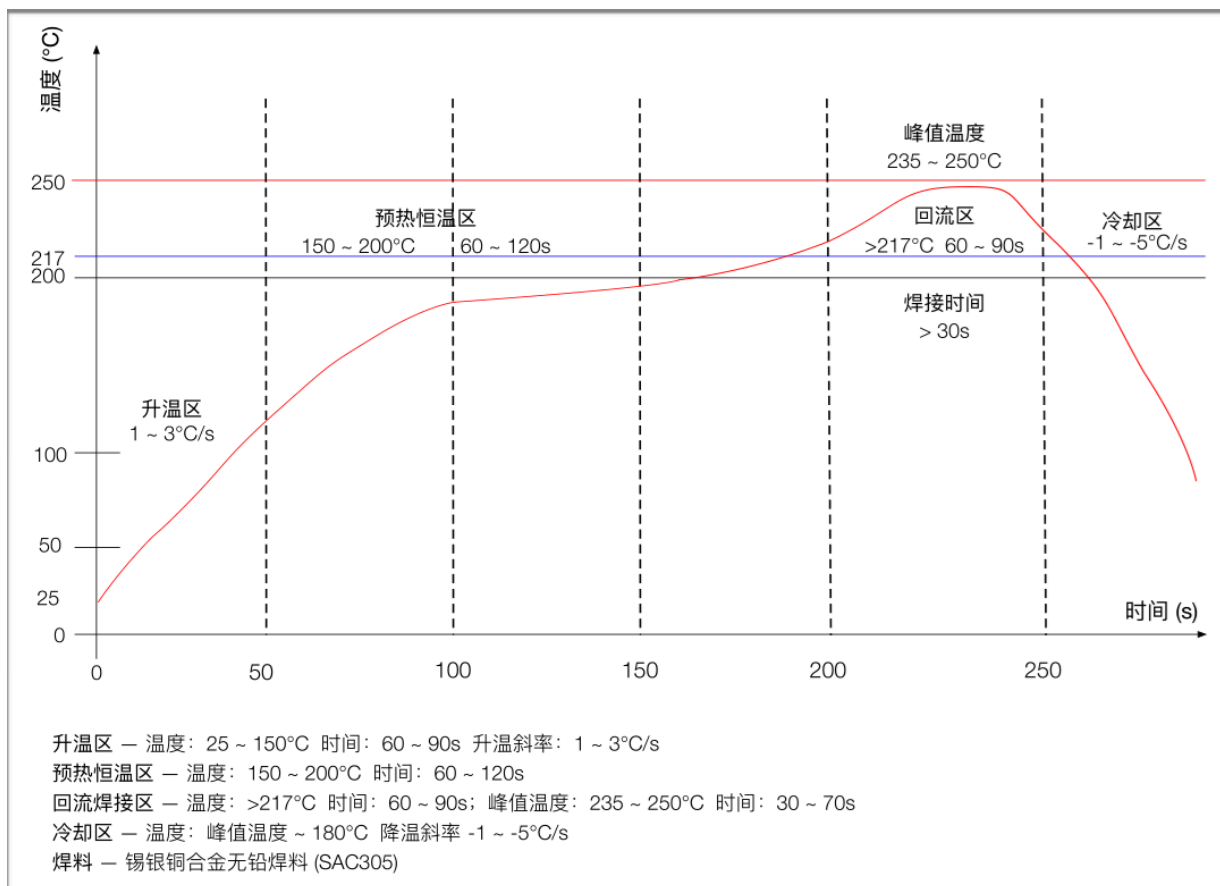
6.2 Module use reminder

- (1) Check the power supply to ensure that it is between the recommended supply voltages. If it exceeds the maximum value, it will cause permanent damage to the module;
- (2) Check the stability of the power supply, and the voltage should not fluctuate significantly and frequently;
- (3) Ensure the anti-static operation during installation and use, and the electrostatic sensitivity of high-frequency devices;
- (4) Ensure that the humidity during installation and use should not be too high, and some components are humidity sensitive devices;
- (5) If there is no special requirement, it is not recommended to use it at too high or too low temperature.

6.3 Interfering factors

- (1) There is co-channel signal interference nearby, please stay away from the interference source or modify the frequency and channel to avoid interference;
- (2) The clock waveform on SPI is not standard, please check whether there is interference on the SPI line, and the SPI bus line should not be too long;
- (3) Unsatisfactory power supply may also cause garbled codes, so the reliability of the power supply must be ensured;
- (4) Extension cords and feeders are of poor quality or too long, which will also cause a high bit error rate

7. Reflow Welding Curve



8. Related models and antenna guide

8.1 Related models

[illegible]

8.2 Antenna recommendation

Antennas play an important role in the communication process, and often inferior antennas will have a great impact on the communication system. Therefore, our company recommends some antennas as supporting our company's wireless modules with better performance and reasonable prices.

Material coding	Type	Frequency	interface	Features
22100003	Spring antenna	433-470MHz	Straight foot welding	Built-in, small size, easy to assemble
22100008	Spring antenna	433-470MHz	Angle welding	Built-in, small size, easy to assemble
22100032	Glue stick antenna	433MHz	SMA internal thread with needle	External omnidirectional antenna, free from interference from the internal environment of the chassis
22100033	Glue stick antenna	470MHz	SMA internal thread with needle	External omnidirectional antenna, free from interference from the internal environment of the chassis
AG-030318-0595	Suction cup antenna	433MHz	SMA internal thread with needle	High gain, extension cable can place the antenna in a better environment
AG-031718-0542	Suction cup antenna	470MHz	SMA internal thread with needle	High gain, extension cable can place the antenna in a better environment

9. Packaging information

Refer to below image, Ra-01SCH package is in Tape/Reel.



10. Contact us

Official website: <https://www.ai-thinker.com>

Development DOCS: <https://docs.ai-thinker.com>

Official Forum: <http://bbs.ai-thinker.com>

Sample purchase: <https://ai-thinker.en.alibaba.com/>

Business cooperation: overseas@aithinker.com

Technical support: support@aithinker.com

Company Address: Room 403,408-410, Block C, Huafeng Smart
Innovation Port, Gushu 2nd Road, Xixiang, Baoan District, Shenzhen.

Tel : 0755-29162996



FCC WARNING

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules.

Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located or operating in conjunction with any other antenna or transmitter.

15.105 Information to the user.

(b) For a Class B digital device or peripheral, the instructions furnished the user shall include the following or similar statement, placed in a prominent location in the text of the manual:

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20

cm between the radiator and your body.

Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment.

This transmitter must not be co-located or operating in conjunction with any other

antenna or transmitter.

The availability of some specific channels and/or operational frequency bands are country dependent and are firmware programmed at the factory to match the intended destination.

The firmware setting is not accessible by the end user.

The final end product must be labelled in a visible area with the following:

“Contains Transmitter Module “2ATPO-01SCH”

Requirement per KDB996369 D03

2.2 List of applicable FCC rules

List the FCC rules that are applicable to the modular transmitter. These are the rules that specifically establish the bands of operation, the power, spurious emissions, and operating fundamental frequencies. DO NOT list compliance to unintentional-radiator rules (Part 15 Subpart B) since that is not a condition of a module grant that is extended to a host manufacturer. See also Section

2.10 below concerning the need to notify host manufacturers that further testing is required.³

Explanation: This module meets the requirements of FCC part 15C (15.247).it Specifically identified AC Power Line Conducted Emission, Radiated Spurious emissions, Band edge and RF Conducted Spurious Emissions, Conducted Peak Output Power, Bandwidth, Power Spectral Density, Antenna Requirement.

2.3 Summarize the specific operational use conditions

Describe use conditions that are applicable to the modular transmitter, including for example any limits on antennas, etc. For example, if point-to-point antennas are used that require reduction in power or compensation for cable loss, then this information must be in the instructions. If the use condition limitations extend to professional users, then instructions must state that this information also extends to the host manufacturer's instruction manual. In addition, certain information may also be needed, such as peak gain per frequency band and minimum gain, specifically for master devices in 5 GHz DFS bands.

Explanation: The product antenna uses an irreplaceable antenna with a gain of 1dBi

2.4 Limited module procedures

The Grantee of a limited module must file with the application for certification a procedure^[6] that describes the proposed method used to ensure host compliance when the limited module is installed in the host product.

If a modular transmitter is approved as a "limited module," then the module manufacturer is responsible for approving the host environment that the limited module is used with. The manufacturer of a limited module must describe, both in the filing and in the installation instructions, the alternative means that the limited module manufacturer uses to verify that the host meets the necessary requirements to satisfy the module limiting conditions.

A limited module manufacturer has the flexibility to define its alternative method to address the conditions that limit the initial approval, such as: shielding, minimum signaling amplitude, buffered modulation/data inputs, or power supply regulation. The alternative method could include that the limited module manufacturer reviews detailed test data or host designs prior to giving the host manufacturer approval. The Grantee can devise a strategy to be approved through a Pre-Approval Guidance (KDB Publication 388624 PAG item MODLIM) inquiry

This limited module procedure is also applicable for RF exposure evaluation when it is necessary to demonstrate compliance in a specific host. The module manufacturer must state how control of the product into which the modular transmitter will be installed and maintained such that full compliance of the product is always ensured. For additional hosts other than the specific host originally granted with a limited module, a Class II permissive change is required on the module grant to register the additional host as a specific host also approved with the module.

Explanation: The module is a single module.

2.5 Trace antenna designs

For a modular transmitter with trace antenna designs, see the guidance in Question 11 of KDB Publication 996369 D02 FAQ – Modules for Micro-Strip Antennas and traces. The integration information shall include for the TCB review the integration instructions for the following aspects: layout of trace design, parts list (BOM), antenna, connectors, and isolation requirements.

a) Information that includes permitted variances (e.g., trace boundary limits, thickness, length, width, shape(s), dielectric constant, and impedance as applicable for each type of antenna); b) Each design shall be considered a different type (e.g., antenna length in multiple(s) of frequency, the wavelength, and antenna shape (traces in phase) can affect antenna gain and must be considered); c) The parameters shall be provided in a manner permitting host manufacturers to design the printed circuit (PC) board layout; d) Appropriate parts by manufacturer and specifications; e) Test procedures for design verification; and f) Production test procedures for ensuring compliance

The module grantee shall provide a notice that any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify the module grantee that they wish to change the

be filed by the grantee, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive required to change application

Explanation: The OEM host can equipped an antenna which antenna gain shall not greater than 2.63dBi

2.6 RF exposure considerations

It is essential for module grantees to clearly and explicitly state the RF exposure conditions that permit a host product manufacturer to use the module. Two types of instructions are required for RF exposure information: (1) to the host product manufacturer, to define the application conditions (mobile, portable – xx cm from a person's body); and (2) additional text needed for the host product manufacturer to provide to end users in their end-product manuals. If RF exposure statements and use conditions are not provided, then the host product manufacturer is required to take responsibility of the module through a change in FCC ID (new application).

Explanation: The module complies with FCC radiofrequency radiation exposure limits for uncontrolled environments. The device is installed and operated with a distance of more than 20 cm between the radiator and your body." This module follows FCC statement design, FCC ID : 2ATPO-01SCH

2.7 Antennas

A list of antennas included in the application for certification must be provided in the instructions. For modular transmitters approved as limited modules, all applicable professional installer instructions must be included as part of the information to the host product manufacturer. The antenna list shall also identify the antenna types (monopole, PIFA, dipole, etc. (note that for example an “omni-directional antenna” is not considered to be a specific “antenna type”).

For situations where the host product manufacturer is responsible for an external connector, for example with an RF pin and antenna trace design, the integration instructions shall inform the installer that unique antenna connector must be used on the Part 15 authorized transmitters used in the host product.

The module manufacturers shall provide a list of acceptable unique connectors.

Explanation: The OEM host can equipped an antenna which antenna gain shall not greater than 2.63dBi

2.8 Label and compliance information

Grantees are responsible for the continued compliance of their modules to the FCC rules. This

includes advising host product manufacturers that they need to provide a physical or e-label stating “Contains FCC ID” with their finished product. See Guidelines for Labeling and User Information for RF Devices – KDB Publication 784748.

Explanation: The host system using this module, should have label in a visible area indicated the following texts: "Contains FCC ID: 2ATPO-01SCH

2.9 Information on test modes and additional testing requirements⁵

Additional guidance for testing host products is given in KDB Publication 996369 D04 Module Integration Guide. Test modes should take into consideration different operational conditions for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product.

The grantee should provide information on how to configure test modes for host product evaluation for different operational conditions for a stand-alone modular transmitter in a host, versus with multiple, simultaneously transmitting modules or other transmitters in a host.

Grantees can increase the utility of their modular transmitters by providing special means, modes, or instructions that simulates or characterizes a connection by enabling a transmitter. This can greatly simplify a host manufacturer’s determination that a module as installed in a host complies with FCC requirements.

Explanation: Ningde lingyang Electronic Technology Co., Ltd. can increase the utility of our modular transmitters by providing instructions that simulates or characterizes a connection by enabling a transmitter.

2.10 Additional testing, Part 15 Subpart B disclaimer

The grantee should include a statement that the modular transmitter is only FCC authorized for the specific rule parts (i.e., FCC transmitter rules) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product

as being Part 15

Subpart B compliant (when it also contains unintentional-radiator digital circuitry), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.

Explanation: The module without unintentional-radiator digital circuitry, so the module does not require an evaluation by FCC Part 15 Subpart B. The host should be evaluated by the FCC Subpart B.